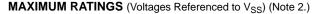
Quad Type D Flip-Flop

The MC14175B quad type D flip—flop is constructed with MOS P—channel and N—channel enhancement mode devices in a single monolithic structure. Each of the four flip—flops is positive—edge triggered by a common clock input (C). An active—low reset input (R) asynchronously resets all flip—flops. Each flip—flop has independent Data (D) inputs and complementary outputs (Q and Q). These devices may be used as shift register elements or as type T flip—flops for counter and toggle applications.

- Complementary Outputs
- Static Operation
- All Inputs and Outputs Buffered
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Output Compatible with Two Low–Power TTL Loads or One Low–Power Schottky TTL Load
- Functional Equivalent to TTL 74175



Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	V _{in} , V _{out} Input or Output Voltage Range (DC or Transient) -0.5 to		V
I _{in} , I _{out}	, l _{out} Input or Output Current ±10 (DC or Transient) per Pin		mA
P _D	Power Dissipation, per Package (Note 3.)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



http://onsemi.com

MARKING DIAGRAMS

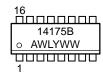


PDIP-16 P SUFFIX CASE 648



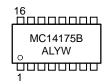


SOIC-16 D SUFFIX CASE 751B





SOEIAJ-16 F SUFFIX CASE 966



A = Assembly Location

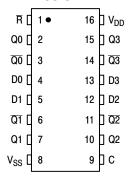
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

ORDERING INFORMATION

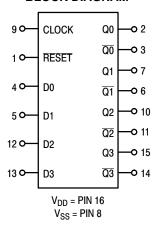
Device	Package	Shipping
MC14175BCP	PDIP-16	2000/Box
MC14175BD	SOIC-16	48/Rail
MC14175BDR2	SOIC-16	2500/Tape & Reel
MC14175BF	SOEIAJ-16	See Note 1.
MC14175BFEL	SOEIAJ-16	See Note 1.

 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

PIN ASSIGNMENT



BLOCK DIAGRAM



TRUTH TABLE

	Inputs		Out	puts	
Clock	Data	Reset	Q	Q	
_	0	1	0	1	
_	1	1	1	0	N.
7	X	1	Q	Q	No Change
Χ	Х	0	0	1	Change

X = Don't Care

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic			V _{DD}	- 5	5°C		25°C		125	5°C	
		Symbol		Min	Min Max	Min	Typ ^(4.)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or V_{DD}	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage ($V_O = 4.5 \text{ or } 0.5 \text{ Vdc}$) ($V_O = 9.0 \text{ or } 1.0 \text{ Vdc}$) ($V_O = 13.5 \text{ or } 1.5 \text{ Vdc}$)	"0" Level	V _{IL}	5.0 10 15	_ _ _	1.5 3.0 4.0	_ _ _	2.25 4.50 6.75	1.5 3.0 4.0	_ _ _	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11		3.5 7.0 11	2.75 5.50 8.25		3.5 7.0 11		Vdc
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 4.6 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$	Source	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		l _{in}	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15	_ _ _	5.0 10 20	_ _ _	0.005 0.010 0.015	5.0 10 20	_ _ _	150 300 600	μAdc
Total Supply Current (5.) (6.) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)		I _T	5.0 10 15			$I_T = (3)$	1.7 μΑ/kHz) f 3.4 μΑ/kHz) f 5.0 μΑ/kHz) f	+ I _{DD}			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

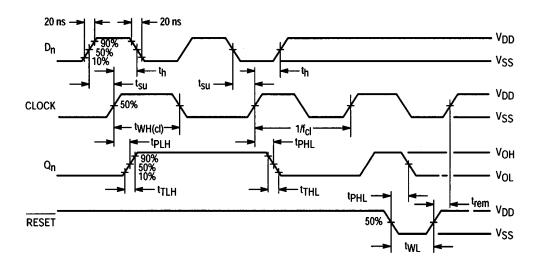
where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.004.

SWITCHING CHARACTERISTICS (7.) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}C$)

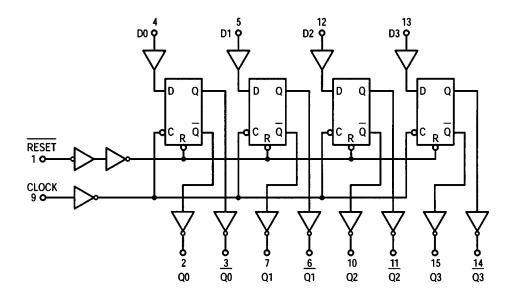
		V _{DD}		T		
Characteristic	Symbol	Vdc	Min	Typ ^(8.)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.35 \text{ ns/pF}) \text{ C}_{L} + 32 \text{ ns}$ $t_{TLH}, t_{THL} = (0.6 \text{ ns/pF}) \text{ C}_{L} + 20 \text{ ns}$ $t_{TLH}, t_{THL} = (0.4 \text{ ns/pF}) \text{ C}_{L} + 20 \text{ ns}$	t _{TLH} , t _{THL}	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Time — Clock to Q, Q t_{PLH} , t_{PHL} = (0.9 ns/pF) C_L + 175 ns t_{PLH} , t_{PHL} = (0.36 ns/pF) C_L + 72 ns t_{PLH} , t_{PHL} = (0.26 ns/pF) C_L + 57 ns	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	220 90 70	400 160 120	ns
Propagation Delay Time — Reset to Q, Q t_{PHL} = (0.9 ns/pF) C_L + 280 ns t_{PHL} = (0.36 ns/pF) C_L + 112 ns t_{PHL} = (0.26 ns/pF) C_L + 87 ns	t _{PHL} , t _{PLH}	5.0 10 15	_ _ _	325 130 100	500 200 150	ns
Clock Pulse Width	t _{WH}	5.0 10 15	250 100 75	110 45 35	_ _ _	ns
Reset Pulse Width	t _{WL}	5.0 10 15	200 80 60	100 40 30	_ _ _	ns
Clock Pulse Frequency	f _{cl}	5.0 10 15		4.5 11 14	2.0 5.0 6.5	mHz
Clock Pulse Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15		_ _ _	15 5.0 4.0	μs
Data Setup Time	t _{su}	5.0 10 15	120 50 40	60 25 20	_ _ _	ns
Data Hold Time	t _h	5.0 10 15	80 40 30	40 20 15	_ _ _	ns
Reset Removal Time	t _{rem}	5.0 10 15	250 100 80	125 50 40	_ _ _	ns

^{7.} The formulas given are for the typical characteristics only at 25°C.
8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

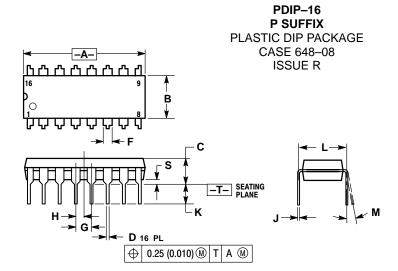
TIMING DIAGRAM



FUNCTIONAL BLOCK DIAGRAM



PACKAGE DIMENSIONS



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION LTO CENTER OF LEADS WHEN FORMED PARALLEL.

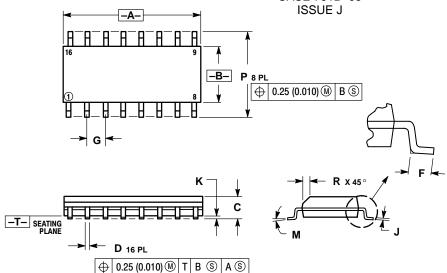
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10 °
S	0.020	0.040	0.51	1.01

SOIC-16 **D SUFFIX**

PLASTIC SOIC PACKAGE CASE 751B-05



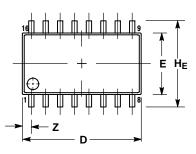
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLERANCING PER AIR Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
- DIMENSION D DUCS NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.

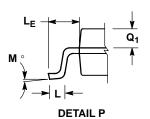
	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

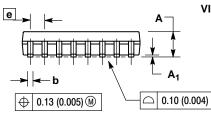
PACKAGE DIMENSIONS

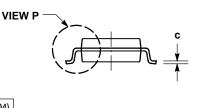
SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE

CASE 966-01 **ISSUE O**









NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- 1. DIMENSIONING AND TOLERANGING FEB 2005
 714.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE
 MOLD FLASH OR PROTRUSIONS AND ARE
 MEASURED AT THE PARTING LINE. MOLD FLASH
 OR PROTRUSIONS SHALL NOT EXCEED 0.15
- OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z		0.78		0.031

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